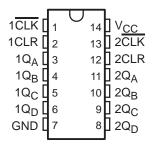
- 2-V to 5.5-V V_{CC} Operation
- Max t_{pd} of 10 ns at 5 V
- Typical V_{OLP} (Output Ground Bounce)
 <0.8 V at V_{CC} = 3.3 V, T_A = 25°C
- Typical V_{OHV} (Output V_{OH} Undershoot)
 >2.3 V at V_{CC} = 3.3 V, T_A = 25°C
- I_{off} Supports Partial-Power-Down-Mode Operation
- Dual 4-Bit Binary Counters With Individual Clocks
- Direct Clear for Each 4-Bit Counter
- Can Significantly Improve System
 Densities by Reducing Counter Package
 Count by 50 Percent
- Latch-Up Performance Exceeds 100 mA Per JESD 78, Class II
- ESD Protection Exceeds JESD 22
 - 2000-V Human-Body Model (A114-A)
 - 200-V Machine Model (A115-A)
 - 1000-V Charged-Device Model (C101)

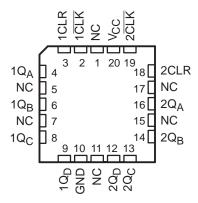
description/ordering information

The 'LV393A devices contain eight flip-flops and additional gating to implement two individual 4-bit counters in a single package. These devices are designed for 2-V to 5.5-V V_{CC} operation.

SN54LV393A . . . J OR W PACKAGE SN74LV393A . . . D, DB, DGV, NS, OR PW PACKAGE (TOP VIEW)



SN54LV393A . . . FK PACKAGE (TOP VIEW)



NC - No internal connection

ORDERING INFORMATION

TA	PACK	AGET	ORDERABLE PART NUMBER	TOP-SIDE MARKING
	colo p	Tube of 50	SN74LV393AD	11/2024
	SOIC - D	Reel of 2500	SN74LV393ADR	LV393A
	SOP - NS	Reel of 2000	SN74LV393ANSR	74LV393A
4000 +- 0500	SSOP - DB	Reel of 2000	SN74LV393ADBR	LV393A
-40°C to 85°C		Tube of 90	SN74LV393APW	
	TSSOP - PW	Reel of 2000	SN74LV393APWR	LV393A
		Reel of 250	SN74LV393APWT	
	TVSOP - DGV	Reel of 2000	SN74LV393ADGVR	LV393A
	CDIP – J	Tube of 25	SNJ54LV393AJ	SNJ54LV393AJ
–55°C to 125°C	CFP – W	Tube of 150	SNJ54LV393AW	SNJ54LV393AW
	LCCC – FK	Tube of 55	SNJ54LV393AFK	SNJ54LV393AFK

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



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description/ordering informaton (continued)

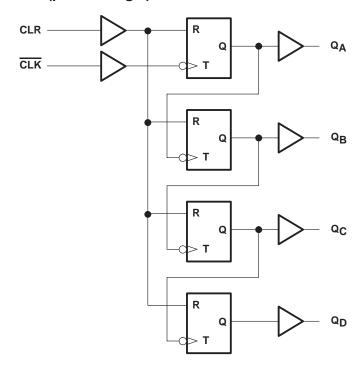
These devices comprise two independent 4-bit binary counters, each having a clear (CLR) and a clock (\overline{\text{CLK}}) input. These devices change state on the negative-going transition of the \overline{\text{CLK}} pulse. N-bit binary counters can be implemented with each package, providing the capability of divide by 256. The 'LV393A devices have parallel outputs from each counter stage so that any submultiple of the input count frequency is available for system timing signals.

These devices are fully specified for partial-power-down applications using I_{off} . The I_{off} circuitry disables the outputs, preventing damaging current backflow through the devices when they are powered down.

FUNCTION TABLE

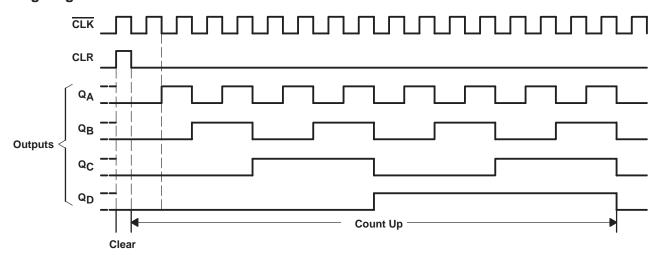
INP	UTS	FUNCTION
CLK	CLR	FUNCTION
1	L	No change
\downarrow	L	Advance to next stage
X	Н	All outputs L

logic diagram, each counter (positive logic)





timing diagram



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CC}		–0.5 V to 7 V
Input voltage range, V _I (see Note 1)		
Output voltage range applied in high or low sta	te, V _O (see Notes 1 and 2)	$-0.5 \text{ V to V}_{CC} + 0.5 \text{ V}$
Output voltage range applied in power-off state	e, VO (see Note 1)	–0.5 V to 7 V
Input clamp current, I_{IK} ($V_I < 0$)		–20 mA
Output clamp current, I _{OK} (V _O < 0)		–50 mA
Continuous output current, I_O ($V_O = 0$ to V_{CC})		±25 mA
Continuous current through V _{CC} or GND		±50 mA
Package thermal impedance, θ _{JA} (see Note 3)	: D package	86°C/W
	DB package	96°C/W
	DGV package	127°C/W
	NS package	
	PW package	113°C/W
Storage temperature range, T _{sta}		–65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output current ratings are observed.

- 2. This value is limited to 7 V maximum.
- 3. The package thermal impedance is calculated in accordance with JESD 51-7.



recommended operating conditions (see Note 4)

			SN54I	_V393A	SN74L	V393A	
			MIN	MAX	MIN	MAX	UNIT
Vcc	Supply voltage		2	5.5	2	5.5	V
		V _{CC} = 2 V	1.5		1.5		
Maria	High level input value	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$	V _{CC} ×0.7		V _{CC} ×0.7		V
VIH	High-level input voltage	$V_{CC} = 3 \text{ V to } 3.6 \text{ V}$	$V_{CC} \times 0.7$		$V_{CC} \times 0.7$		V
		$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$	$V_{CC} \times 0.7$		$V_{CC} \times 0.7$		
		V _{CC} = 2 V		0.5		0.5	
	Low level input voltage	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$		$V_{CC} \times 0.3$		$V_{CC} \times 0.3$	V
V_{IL}	Low-level input voltage	V _{CC} = 3 V to 3.6 V		V _{CC} ×0.3		$V_{CC} \times 0.3$	V
		V _{CC} = 4.5 V to 5.5 V		V _{CC} ×0.3		$V_{CC} \times 0.3$	
٧ı	Input voltage		0	5.5	0	5.5	V
VO	Output voltage		0	[₹] Vcc	0	VCC	V
		V _{CC} = 2 V	3	-50		-50	μΑ
	High lavel autout aumant	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$	90	-2		-2	
ЮН	High-level output current	V _{CC} = 3 V to 3.6 V	D. C.	-6		-6	mA
		$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$		-12		-12	
		V _{CC} = 2 V		50		50	μΑ
	Law law bandantan and	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$		2		2	
lOL	Low-level output current	V _{CC} = 3 V to 3.6 V		6		6	mA
		V _{CC} = 4.5 V to 5.5 V		12		12	
		V _{CC} = 2.3 V to 2.7 V		200		200	
Δt/Δν	Input transition rise or fall rate	$V_{CC} = 3 \text{ V to } 3.6 \text{ V}$		100		100	ns/V
		V _{CC} = 4.5 V to 5.5 V		20		20	
TA	Operating free-air temperature		-55	125	-40	85	°C

NOTE 4: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

	TEGT CONDITIONS		SN5	4LV393A		SN74	LV393A	1	
PARAMETER	TEST CONDITIONS	VCC	MIN	TYP	MAX	MIN	TYP	MAX	UNIT
	I _{OH} = -50 μA	2 V to 5.5 V	V _{CC} -0.1			V _{CC} -0.1			
	$I_{OH} = -2 \text{ mA}$	2.3 V	2			2			.,
VOH	$I_{OH} = -6 \text{ mA}$	3 V	2.48			2.48			V
	I _{OH} = -12 mA	4.5 V	3.8	F		3.8			
	I _{OL} = 50 μA	2 V to 5.5 V		FI	0.1			0.1	
	$I_{OL} = 2 \text{ mA}$	2.3 V		Q	0.4			0.4	V
V_{OL}	I _{OL} = 6 mA	3 V	9	ý,	0.44			0.44	V
	I _{OL} = 12 mA	4.5 V	2		0.55			0.55	
lį	V _I = 5.5 V or GND	0 to 5.5 V	8		±1			±1	μΑ
ICC	$V_I = V_{CC}$ or GND, $I_O = 0$	5.5 V			20			20	μΑ
l _{off}	V_I or $V_O = 0$ to 5.5 V	0			5			5	μΑ
C _i	V _I = V _{CC} or GND	3.3 V		1.8			1.8		pF

timing requirements over recommended operating free-air temperature range, V_{CC} = 2.5 V \pm 0.2 V (unless otherwise noted) (see Figure 1)

			$T_A = 2$	25°C	SN54L	V393A	SN74L\	/393A	LINIT
			MIN	MAX	MIN	MAX	MIN	MAX	UNIT
	Dulan demotion	CLK high or low	5		5	JC'N	5		
τ _W	Pulse duration	CLR high	5		5	JIE.	5		ns
t _{su}	Setup time	CLR inactive before CLK↓	6		6		6	·	ns

timing requirements over recommended operating free-air temperature range, V_{CC} = 3.3 V \pm 0.3 V (unless otherwise noted) (see Figure 1)

			$T_A = 2$	25°C	SN54L\	/393A	SN74L\	/393A	LINUT
			MIN	MAX	MIN	MAX	MIN	MAX	UNIT
	Pode a demotion	CLK high or low	5		5	10,7	5		
t _W	Pulse duration	CLR high	5		5	IIE.	5		ns
t _{su}	Setup time	CLR inactive before CLK↓	5		5		5		ns

timing requirements over recommended operating free-air temperature range, V_{CC} = 5 V \pm 0.5 V (unless otherwise noted) (see Figure 1)

			T _A = 2	25°C	SN54L	V393A	SN74L\	/393A	
			MIN	MAX	MIN	MAX	MIN	MAX	UNIT
	D	CLK high or low	5		5 ्	10'N	5		
t _W	Pulse duration	CLR high	5		5	JIE.	5		ns
t _{su}	Setup time	CLR inactive before CLK↓	4		4		4		ns

switching characteristics over recommended operating free-air temperature range, V_{CC} = 2.5 V \pm 0.2 V (unless otherwise noted) (see Figure 1)

	FROM	то	LOAD	T,	Δ = 25°C	;	SN54L	/393A	SN74L\	/393A	
PARAMETER	(INPUT)	(OUTPUT)	CAPACITANCE	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
			C _L = 15 pF	50*	90*		40*		40		N 41 1-
f _{max}			C _L = 50 pF	30	70		25		25		MHz
		Q_A			7.1*	17.7*	1*	20.5*	1	20.5	
	CLK	QB			8.5*	20.3*	1*	23.5*	1	23.5	
^t pd	CLK	QC	C _L = 15 pF		10*	22.5*	1*	26*	1	26	ns
		QD			11.1*	24.2*	1*	28*	1	28	
^t PHL	CLR	Qn			6.7*	14.8*	150	17*	1	17	
		Q_A			9.3	21.3	01	24.5	1	24.5	
	CLK	QB			10.9	23.9	Q 1	27.5	1	27.5	
^t pd	CLK	QC	C _L = 50 pF		12.3	26.1	1	30	1	30	ns
		QD			13.4	27.8	1	32	1	32	
^t PHL	CLR	Q _n			9.1	17.4	1	20	1	20	

^{*} On products compliant to MIL-PRF-38535, this parameter is not production tested.



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switching characteristics over recommended operation free-air temperature range, V_{CC} = 3.3 V \pm 0.3 V (unless otherwise noted) (see Figure 1)

	FROM	то	LOAD	T,	Վ = 25° C	;	SN54L	V393A	SN74L	/393A	
PARAMETER	(INPUT)	(OUTPUT)	CAPACITANCE	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
£			C _L = 15 pF	75*	130*		65*		65		MHz
f _{max}			$C_L = 50 pF$	45	105		35		35		IVITZ
		Q_A			5.1*	13.2*	1*	15.5*	1	15.5	
		QB			6*	15.8*	1*	18.5*	1	18.5	
t _{pd}	CLK	QC	C _L = 15 pF		7*	18*	1*	21*	1	21	ns
		Q_{D}			7.7*	19.7*	1*	23*	1	23	
^t PHL	CLR	Qn			5.1*	12.3*	2)	14.5*	1	14.5	
		Q _A			6.7	16.7	2 ₀	19	1	19	
	CLK	QB			7.8	19.3	Q 1	22	1	22	
^t pd	CLK	QC	C _L = 50 pF		8.7	21.5	1	24.5	1	24.5	ns
		QD			9.5	23.2	1	26.5	1	26.5	
^t PHL	CLR	Qn			6.8	15.8	1	18	1	18	

^{*} On products compliant to MIL-PRF-38535, this parameter is not production tested.

switching characteristics over recommended operating free-air temperature range, V_{CC} = 5 V \pm 0.5 V (unless otherwise noted) (see Figure 1)

00	•		, ,	•	•						
24244555	FROM	то	LOAD	T,	4 = 25°C	;	SN54L\	/393A	SN74L	/393A	
PARAMETER	(INPUT)	(OUTPUT)	CAPACITANCE	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
			C _L = 15 pF	125*	185*		105*		105		N 41 1-
f _{max}			C _L = 50 pF	85	150		75		75		MHz
		Q _A			3.7*	8.5*	1*	10*	1	10	
		QB			4.3*	9.8*	1*	11.5*	1	11.5	
^t pd	CLK	QC	C _L = 15 pF		4.9*	11.2*	1*	13*	1	13	ns
		QD			5.3*	12.5*	1* 4	14.5*	1	14.5	
t _{PHL}	CLR	Qn			3.9*	8.1*	150	9.5*	1	9.5	
		Q _A			4.9	10.5	01	12	1	12	
		QB			5.6	11.8	Q 1	13.5	1	13.5	
^t pd	CLK	QC	C _L = 50 pF		6.2	13.2	1	15	1	15	ns
		Q_{D}			6.6	14.5	1	16.5	1	16.5	
t _{PHL}	CLR	Qn			5.2	10.1	1	11.5	1	11.5	

^{*} On products compliant to MIL-PRF-38535, this parameter is not production tested.



noise characteristics, V_{CC} = 3.3 V, C_L = 50 pF, T_A = 25°C (see Note 5)

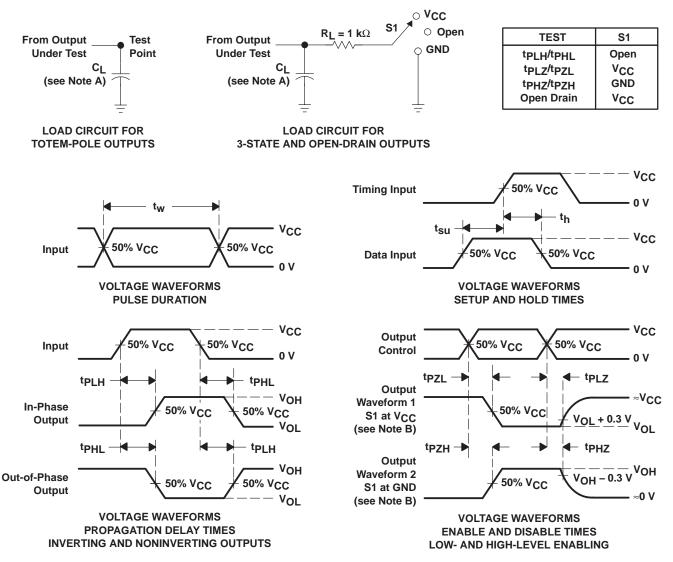
	DADAMETED	SN	74LV393	A	LINUT
	PARAMETER	MIN	TYP	MAX	UNIT
VOL(P)	Quiet output, maximum dynamic VOL		0.3	8.0	V
V _{OL(V)}	Quiet output, minimum dynamic V _{OL}		-0.2	-0.8	V
VOH(V)	Quiet output, minimum dynamic VOH		2.8		V
V _{IH(D)}	High-level dynamic input voltage	2.31			V
V _{IL(D)}	Low-level dynamic input voltage			0.99	V

NOTE 5: Characteristics are for surface-mount packages only.

operating characteristics, $T_A = 25^{\circ}C$

	PARAMETER	TEST CO	NDITIONS	VCC	TYP	UNIT
C _{pd}	Dower dissination conscitance	C _L = 50 pF,	f 40 MH I-	3.3 V	15.2	pF
	Power dissipation capacitance		f = 10 MHz	5 V	17.3	

PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_I includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
- All input pulses are supplied by generators having the following characteristics: $PRR \le 1 \text{ MHz}$, $Z_O = 50 \Omega$, $t_f \le 3 \text{ ns}$, $t_f \le 3 \text{ ns}$.
- D. The outputs are measured one at a time, with one input transition per measurement.
- E. tpLz and tpHz are the same as tdis.
- F. tpz and tpzH are the same as ten.
- G. tpHL and tpLH are the same as tpd.
- H. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms







10-Jun-2014

PACKAGING INFORMATION

Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
SN74LV393AD	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	LV393A	Samples
SN74LV393ADBR	ACTIVE	SSOP	DB	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	LV393A	Samples
SN74LV393ADG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	LV393A	Samples
SN74LV393ADGVR	ACTIVE	TVSOP	DGV	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	LV393A	Samples
SN74LV393ADR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	LV393A	Samples
SN74LV393ANSR	ACTIVE	so	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	74LV393A	Samples
SN74LV393APW	ACTIVE	TSSOP	PW	14	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	LV393A	Samples
SN74LV393APWR	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	LV393A	Samples
SN74LV393APWRE4	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	LV393A	Samples
SN74LV393APWRG4	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	LV393A	Samples
SN74LV393APWT	ACTIVE	TSSOP	PW	14	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	LV393A	Samples

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.





10-Jun-2014

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above. **Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead/Ball Finish Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

OTHER QUALIFIED VERSIONS OF SN74LV393A:

Automotive: SN74LV393A-Q1

Enhanced Product: SN74LV393A-EP

NOTE: Qualified Version Definitions:

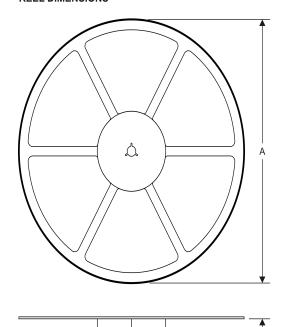
- Automotive Q100 devices qualified for high-reliability automotive applications targeting zero defects
- Enhanced Product Supports Defense, Aerospace and Medical Applications

PACKAGE MATERIALS INFORMATION

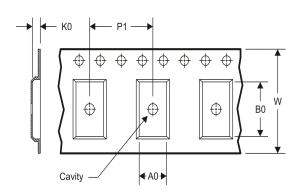
www.ti.com 14-Jul-2012

TAPE AND REEL INFORMATION

REEL DIMENSIONS



TAPE DIMENSIONS



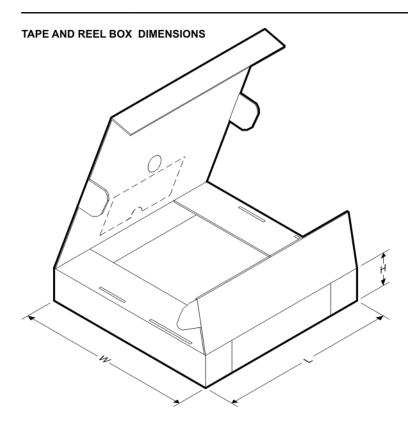
A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

TAPE AND REEL INFORMATION

*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LV393ADBR	SSOP	DB	14	2000	330.0	16.4	8.2	6.6	2.5	12.0	16.0	Q1
SN74LV393ADGVR	TVSOP	DGV	14	2000	330.0	12.4	6.8	4.0	1.6	8.0	12.0	Q1
SN74LV393ADR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
SN74LV393ANSR	SO	NS	14	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
SN74LV393APWR	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
SN74LV393APWT	TSSOP	PW	14	250	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1

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*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LV393ADBR	SSOP	DB	14	2000	367.0	367.0	38.0
SN74LV393ADGVR	TVSOP	DGV	14	2000	367.0	367.0	35.0
SN74LV393ADR	SOIC	D	14	2500	367.0	367.0	38.0
SN74LV393ANSR	SO	NS	14	2000	367.0	367.0	38.0
SN74LV393APWR	TSSOP	PW	14	2000	367.0	367.0	35.0
SN74LV393APWT	TSSOP	PW	14	250	367.0	367.0	35.0

DGV (R-PDSO-G**)

24 PINS SHOWN

PLASTIC SMALL-OUTLINE



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15 per side.

D. Falls within JEDEC: 24/48 Pins – MO-153 14/16/20/56 Pins – MO-194

D (R-PDSO-G14)

PLASTIC SMALL OUTLINE



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AB.



D (R-PDSO-G14)

PLASTIC SMALL OUTLINE

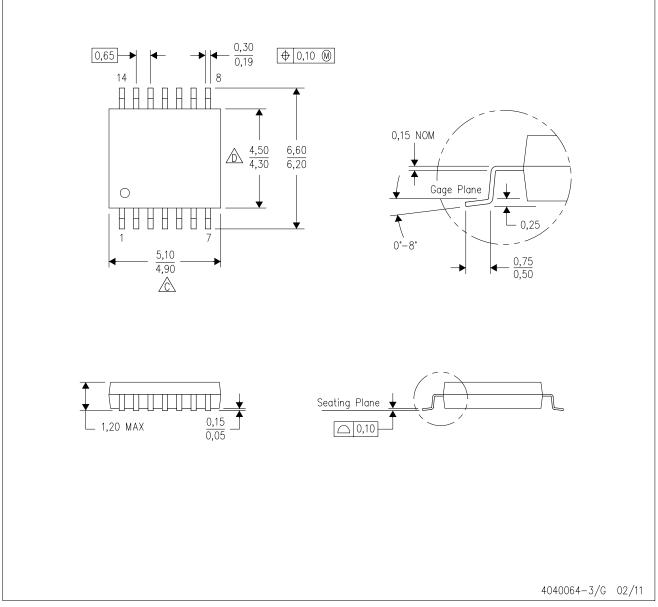


- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



PW (R-PDSO-G14)

PLASTIC SMALL OUTLINE

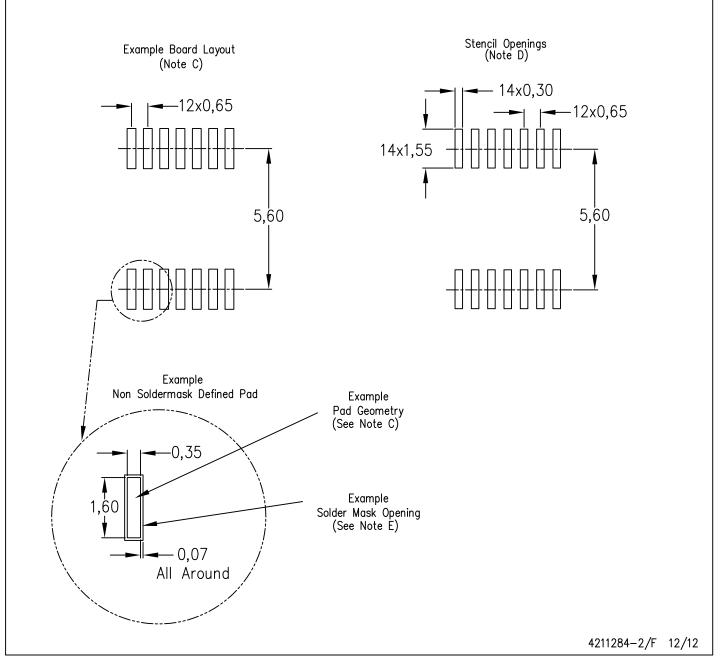


- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M—1994.
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0,15 each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.
- E. Falls within JEDEC MO-153



PW (R-PDSO-G14)

PLASTIC SMALL OUTLINE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



MECHANICAL DATA

NS (R-PDSO-G**)

14-PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



DB (R-PDSO-G**)

PLASTIC SMALL-OUTLINE

28 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.

D. Falls within JEDEC MO-150

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